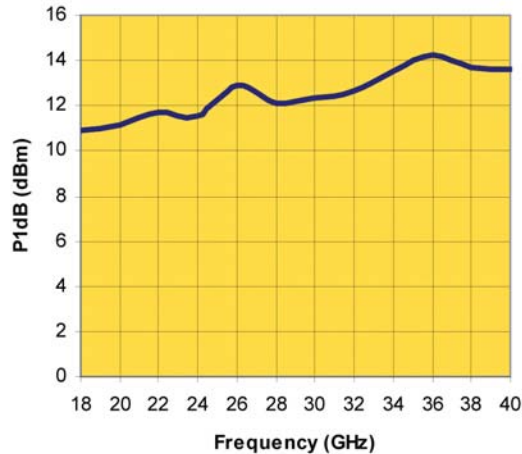


**GaAs HEMT MMIC LOW NOISE
AMPLIFIER, 18 - 40 GHz**

On-Wafer P1dB vs. Frequency



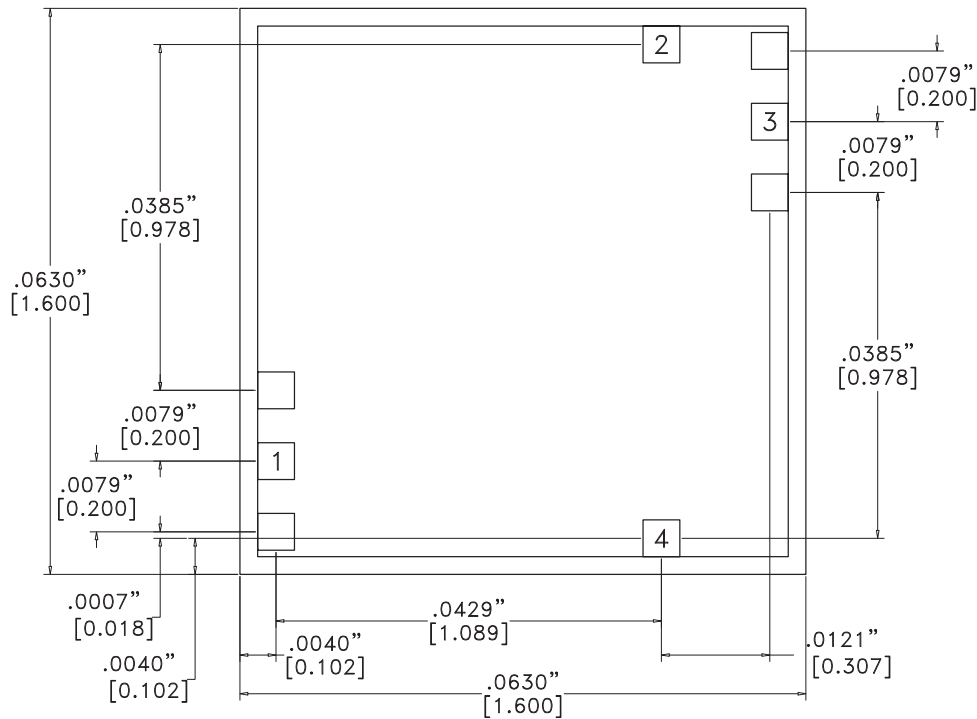
Absolute Maximum Ratings

Drain Bias Voltage	+5.5 Vdc
Drain Bias Current	60 mA
RF Input Power	10 dBm
Thermal Resistance (channel to die bottom)	201.2 °C/W
Channel Temperature	180 °C
Storage Temperature	-65 to +150 °C
Operating Temperature	-55 to +85 °C



**ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS**

Outline Drawing



Die Packaging Information [1]

Standard	Alternate
GP-1 (Gel Pack)	[2]

[1] Refer to the "Packaging Information" section for die packaging dimensions.

[2] For alternate packaging information contact Hittite Microwave Corporation.

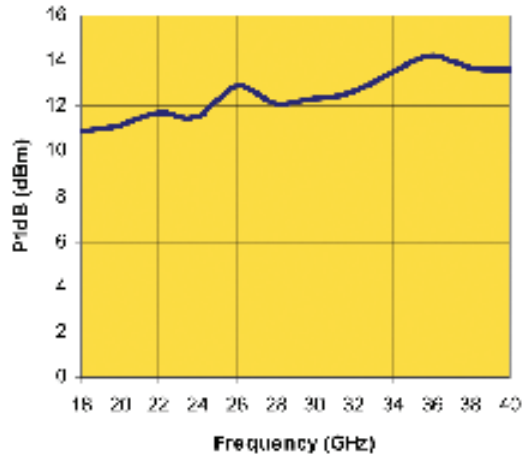
NOTES:

1. ALL DIMENSIONS ARE IN INCHES [MM].
2. TYPICAL BOND PAD IS .004" SQUARE.
3. BACKSIDE METALLIZATION: GOLD.
4. BACKSIDE METAL IS GROUND.
5. BOND PAD METALLIZATION: GOLD.
6. CONNECTION NOT REQUIRED FOR UNLABELED BOND PADS.
7. OVERALL DIE SIZE ±.002"

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On-Wafer P1dB vs. Frequency



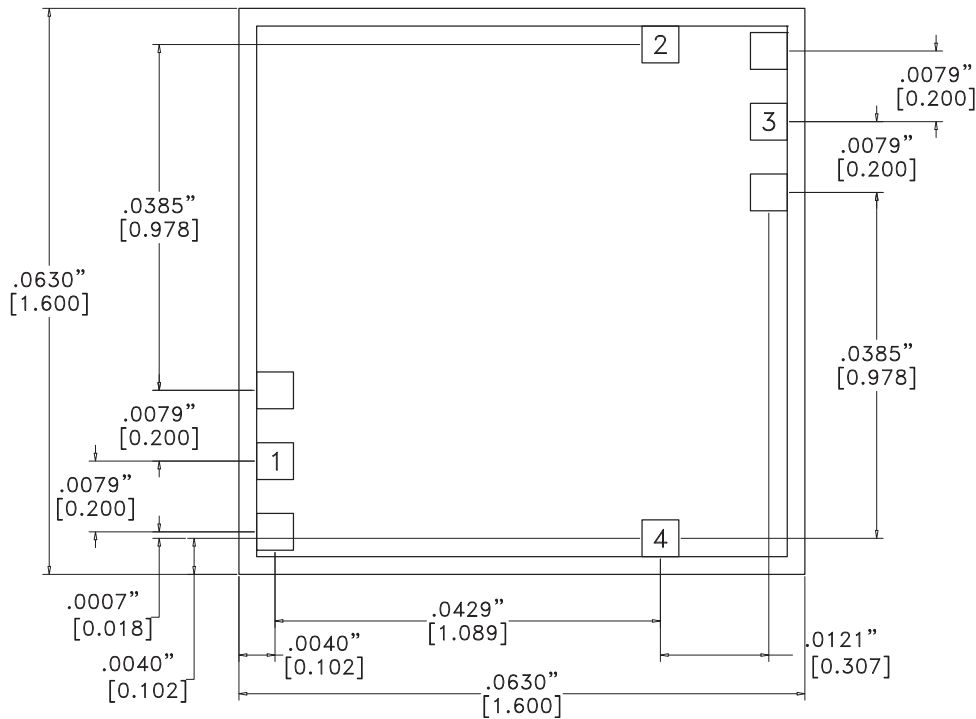
Absolute Maximum Ratings

Drain Bias Voltage	+5.5 Vdc
Drain Bias Current	60 mA
RF Input Power	10 dBm
Thermal Resistance (channel to die bottom)	124 °C/W
Channel Temperature	180 °C
Storage Temperature	-65 to +150 °C
Operating Temperature	-55 to +85 °C



ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

Outline Drawing



Die Packaging Information ^[1]

Standard	Alternate
GP-1 (Gel Pack)	[2]

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